

ABSTRACT

A substrate electroplating apparatus comprises at least two anodes, at least two power supplies, and at least one control switch. Wherein, the anodes are in one-to-one correspondence with the power supplies, each anode is connected to the positive electrode of the corresponding power supply, and the control switch is configured to connect the at least two anodes to the positive electrode of the same power supply when the control switch is energized. By switching between a single power supply and multiple power supplies, the problem of current fluctuation caused by mutual interference between multiple power supplies during the electroplating entry stage is effectively solved without affecting the electroplating effect in the multi-anode electroplating process stage.